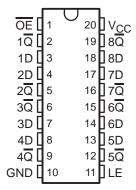
- State-of-the-Art *EPIC-IIB™* BiCMOS Design **Significantly Reduces Power Dissipation**
- Latch-Up Performance Exceeds 500 mA Per **JEDEC Standard JESD-17**
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- **Package Options Include Plastic** Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package

description

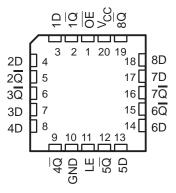
These octal transparent D-type latches with 3-state outputs are designed specifically for drivina highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

When the latch-enable (LE) input is high, the Q outputs follow the complements of the data (D) inputs. When LE is taken low, the \overline{Q} outputs are latched at the inverse of the levels at the D inputs.

SN54ABT533 . . . J OR W PACKAGE SN74ABT533A...DB, DW, N, OR PW PACKAGE (TOP VIEW)



SN54ABT533 . . . FK PACKAGE (TOP VIEW)



A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

OE does not affect the internal operations of the latches. Previously stored data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT533 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT533A is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

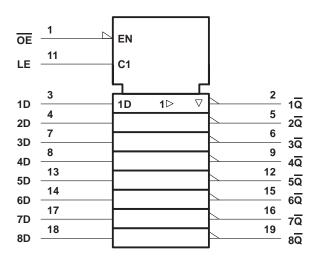
EPIC-IIB is a trademark of Texas Instruments Incorporated



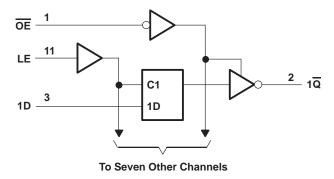
FUNCTION TABLE (each latch)

| | INPUTS | | | | | | | | | |
|----|--------|---|----------------------|--|--|--|--|--|--|--|
| OE | LE | D | OU <u>TP</u> UT Q | | | | | | | |
| L | Н | Н | L | | | | | | | |
| L | Н | L | Н | | | | | | | |
| L | L | Χ | \overline{Q}_0 | | | | | | | |
| Н | X | Χ | Z | | | | | | | |

logic symbol†



logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

| Supply voltage range, V _{CC} | | –0.5 V to 7 V |
|---|------------------------------------|---------------|
| Input voltage range, V _I (see Note 1) | | –0.5 V to 7 V |
| Voltage range applied to any output in the high | or power-off state, V _O | |
| Current into any output in the low state, IO: SN | 54ABT533 | 96 mA |
| SN | 74ABT533A | |
| Input clamp current, I _{IK} (V _I < 0) | | |
| Output clamp current, I_{OK} ($V_O < 0$) | | |
| Package thermal impedance, θ _{JA} (see Note 2): | DB package | 115°C/W |
| | DW package | 97°C/W |
| | N package | 67°C/W |
| | PW package | |
| Storage temperature range, T _{stq} | | |

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

| | | SN54A | SN54ABT533 | | T533A | UNIT |
|-----------------|------------------------------------|-------------|------------|-----|-------|------|
| | | MIN | MAX | MIN | MAX | UNIT |
| VCC | Supply voltage | 4.5 | 5.5 | 4.5 | 5.5 | V |
| VIH | High-level input voltage | 2 | | 2 | | V |
| V _{IL} | Low-level input voltage | | 0.8 | | 0.8 | V |
| VI | Input voltage | 0 | VCC | 0 | VCC | V |
| loh | High-level output current | | -24 | | -32 | mA |
| loL | Low-level output current | | 48 | | 64 | mA |
| Δt/Δν | Input transition rise or fall rate | | 10 | | 10 | ns/V |
| TA | Operating free-air temperature | – 55 | 125 | -40 | 85 | °C |

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| DADAMETER | TEST CONDITIONS | | | | _A = 25°C | ; | SN54A | BT533 | SN74AB | T533A | UNIT |
|------------------|---|--|------------------|-----|---------------------|-------|-------|-------|--------|-------|------|
| PARAMETER | | TEST CONDITIO | ONS | MIN | TYP [†] | MAX | MIN | MAX | MIN | MAX | UNIT |
| VIK | $V_{CC} = 4.5 \text{ V},$ | CC = 4.5 V, I _I = -18 mA | | | | -1.2 | | -1.2 | | -1.2 | V |
| | $V_{CC} = 4.5 V$, | IOH = -3 mA | | 2.5 | | | 2.5 | | 2.5 | | |
| \/ | V _C C = 5 V, | IOH = -3 mA | | 3 | | | 3 | | 3 | | V |
| VOH | V _{CC} = 4.5 V | I _{OH} = -24 mA | | 2 | | | 2 | | | | V |
| | VCC = 4.5 V | $I_{OH} = -32 \text{ mA}$ | | 2* | | | | | 2 | | |
| Vai | V00 - 4 5 V | I _{OL} = 48 mA | | | | 0.55 | | 0.55 | | | V |
| VOL | V _{CC} = 4.5 V | I _{OL} = 64 mA | | | | 0.55* | | | | 0.55 | V |
| V _{hys} | | | | | 100 | | | | | | mV |
| ΙΙ | $V_{CC} = 5.5 \text{ V},$ | $V_I = V_{CC}$ or GN | ND | | | ±1 | | ±1 | | ±1 | μΑ |
| lozh | V _{CC} = 5.5 V, | V _O = 2.7 V | | | | 10 | | 10 | | 10 | μΑ |
| lozL | V _{CC} = 5.5 V, | V _O = 0.5 V | | | | -10 | | -10 | | -10 | μΑ |
| l _{off} | $V_{CC} = 0$, | V _I or V _O ≤ 4.5 \ | J | | | ±150 | | | | ±150 | μΑ |
| ICEX | $V_{CC} = 5.5 V$, | V _O = 5.5 V | Outputs high | | | 50 | | 50 | | 50 | μΑ |
| IO [‡] | $V_{CC} = 5.5 V$, | V _O = 2.5 V | | -50 | -140 | -180 | -50 | -180 | -50 | -180 | mA |
| | | _ | Outputs high | | 1 | 250 | | 250 | | 250 | μΑ |
| ICC | V _{CC} = 5.5 V, I _C V _I = V _{CC} or GI | • | Outputs low | | 24 | 30 | | 30 | | 30 | mA |
| | 1 1 2 1 2 1 2 1 | 1 D | Outputs disabled | | 0.5 | 250 | | 250 | | 250 | μΑ |
| | V _{CC} = 5.5 V, | | Outputs high | | | 1.5 | | 1.5 | | 1.5 | |
| ΔICC§ | One input at 3.4 V, | | Outputs low | | | 1.5 | | 1.5 | | 1.5 | mA |
| | Other inputs at | V _{CC} or GND | Outputs disabled | | | 1.5 | | 1.5 | | 1.5 | |
| C _i | $V_{I} = 2.5 \text{ V or } 0.$ | V _I = 2.5 V or 0.5 V | | | 3.5 | | | | | | pF |
| Co | $V_0 = 2.5 \text{ V or } 0$ | 0.5 V | | | 6.5 | | | | | | pF |

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.



[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

SN54ABT533, SN74ABT533A OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

SCBS186D - JANUARY 1991 - REVISED JANUARY 1997

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

| | | | | SN54A | BT533 | | |
|-----------------|-----------------------------|-------------|-------------------|----------------|-------|-----|------|
| | | | V _{CC} = | = 5 V, 25°C | MIN | MAX | UNIT |
| | | | MIN | MAX | | | |
| t _W | Pulse duration, LE high | | 3.3 | | 3.3 | | ns |
| t _{su} | Setup time, data before LE↓ | High or low | 2.1 | | 2.1 | | ns |
| t _h | Hold time, data after LE↓ | High or low | 1.5 | | 1.5 | | ns |

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

| | | | | SN74AE | 3T533A | | |
|-----------------|-----------------------------|-------------|-------------------|----------------|--------|-----|------|
| | | | V _{CC} : | = 5 V, 25°C | MIN | MAX | UNIT |
| | | | MIN | MAX | | | |
| t _W | Pulse duration, LE high | | 3.3 | | 3.3 | | ns |
| t _{su} | Setup time, data before LE↓ | High or low | 2.1 | | 2.1 | | ns |
| th | Hold time, data after LE↓ | High or low | 2.1 | | 2.1 | | ns |

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

| | | | | SN | 54ABT5 | 33 | | |
|------------------|-----------------|----------------|----------------|----------------------|---------|-----|-----|------|
| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V ₍ | CC = 5 \ 4 = 25°C | /, } | MIN | MAX | UNIT |
| | | | MIN | TYP | MAX | | | |
| tpLH | D | Q | 1.9 | 4.2 | 5.4 | 1.9 | 6.7 | ns |
| t _{PHL} | В | Q | 3.1 | 4.9 | 6.3 | 3.1 | 6.9 | 115 |
| tpLH | 1.5 | Q | 2.7 | 4.9 | 6.2 | 2.7 | 7.6 | ns |
| t _{PHL} | LE | Q | 3.5 | 5.4 | 6.8 | 3.5 | 7.5 | 115 |
| ^t PZH | ŌĒ | Q | 1.6 | 3.7 | 4.8 | 1.6 | 5.8 | ns |
| tPZL | OE . | Q | 2.4 | 4.2 | 6.2 | 2.4 | 6.9 | 115 |
| t _{PHZ} | ŌĒ | Q | 2.8 | 5.1 | 6.2 | 2.8 | 7.2 | ne |
| t _{PLZ} | UE UE | l Q | 2 | 4.1 | 6 | 2 | 6.9 | ns |

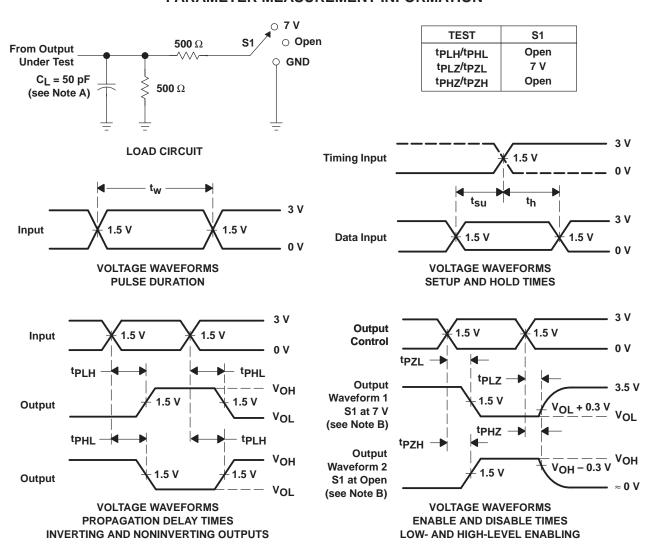
SN54ABT533, SN74ABT533A OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

SCBS186D - JANUARY 1991 - REVISED JANUARY 1997

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V ₍ | CC = 5 V 4 = 25°C | /, ; | MIN | MAX | UNIT |
|------------------|-----------------|----------------|----------------|----------------------|---------|-----|-----|------|
| | | | MIN | TYP | MAX | | | |
| t _{PLH} | D | Q | 1.7 | 4.2 | 5.4 | 1.7 | 6.4 | ns |
| t _{PHL} | В | Q Q | 2.6 | 4.9 | 6.3 | 2.6 | 6.6 | 115 |
| t _{PLH} | | Q | | 4.9 | 6.2 | 2.7 | 7.3 | 20 |
| t _{PHL} | LE | l ^q | 3.5 | 5.4 | 6.8 | 3.5 | 7.3 | ns |
| ^t PZH | ŌĒ | DE Q | | 3.7 | 4.8 | 1.6 | 5.7 | 20 |
| tPZL | OE . | Q | 2.4 | 4.2 | 6.2 | 2.4 | 6.7 | ns |
| ^t PHZ | ŌĒ | Q | 1.6 | 5.1 | 6.2 | 1.6 | 6.9 | ns |
| tPLZ | J ∪E | | 2 | 4.1 | 6 | 2 | 6.5 | 115 |

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{Q} = 50 Ω , t_{f} \leq 2.5 ns, t_{f} \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



www.ti.com 10-Jun-2022

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan | Lead finish/ Ball material | MSL Peak Temp | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|------------|--------------|--------------------|------|----------------|---------------------|-------------------------------|--------------------|--------------|--|---------|
| 5962-9584301Q2A | ACTIVE | LCCC | FK | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962- 9584301Q2A SNJ54 ABT533FK | Samples |
| 5962-9584301QRA | ACTIVE | CDIP | J | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9584301QR A SNJ54ABT533J | Samples |
| SN74ABT533AN | ACTIVE | PDIP | N | 20 | 20 | RoHS & Non-Green | NIPDAU | N / A for Pkg Type | -40 to 85 | SN74ABT533AN | Samples |
| SN74ABT533APWR | ACTIVE | TSSOP | PW | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AB533A | Samples |
| SNJ54ABT533FK | ACTIVE | LCCC | FK | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962- 9584301Q2A SNJ54 ABT533FK | Samples |
| SNJ54ABT533J | ACTIVE | CDIP | J | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9584301QR A SNJ54ABT533J | Samples |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



PACKAGE OPTION ADDENDUM

www.ti.com 10-Jun-2022

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022

TAPE AND REEL INFORMATION





| A0 | Dimension designed to accommodate the component width |
|----|---|
| В0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

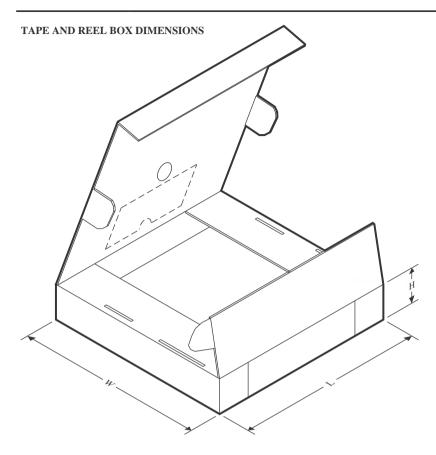


*All dimensions are nominal

| | Device | Package Type | Package Drawing | | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---|----------------|-----------------|--------------------|----|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| ĺ | SN74ABT533APWR | TSSOP | PW | 20 | 2000 | 330.0 | 16.4 | 6.95 | 7.0 | 1.4 | 8.0 | 16.0 | Q1 |

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022



*All dimensions are nominal

| Ì | Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---|----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| ı | SN74ABT533APWR | TSSOP | PW | 20 | 2000 | 356.0 | 356.0 | 35.0 |

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022

TUBE



*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (µm) | B (mm) |
|-----------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| 5962-9584301Q2A | FK | LCCC | 20 | 1 | 506.98 | 12.06 | 2030 | NA |
| SN74ABT533AN | N | PDIP | 20 | 20 | 506 | 13.97 | 11230 | 4.32 |
| SNJ54ABT533FK | FK | LCCC | 20 | 1 | 506.98 | 12.06 | 2030 | NA |



SMALL OUTLINE PACKAGE



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
 C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2023, Texas Instruments Incorporated